Please add new claims 3 - 8 as follows:

--3. A single-sided paper phenolic resin copper-clad laminate as claimed in claim 1, wherein said resist is formed of a synthetic resin.--

--4. A single-sided paper phenolic resin copper-clad laminate as claimed in claim 2, wherein said resist is formed of a synthetic resin. --

--5. A single-sided paper phenolic resin copper-clad laminate as claimed in claim 3, wherein the synthetic resin is an epoxy resin. --

--6. A single-sided paper phenolic resin copper-clad laminate as claimed in claim 4, wherein the synthetic resin is an epoxy resin. --

--7. A single-sided paper phenolic resin copper-clad laminate as claimed in claim 1, wherein the terminals of electric components are soldered with lead-free solder. --

--8. A single-sided paper phenolic resin copper-clad laminate as claimed in claim 2, wherein the terminals of electric components are soldered with lead-free solder. --

REMARKS

Claims 1-8 are now pending. Claim 1 is amended and claims 3-8 are added herein. The amendments are supported at, for example, paragraphs [0005], [0006], [0038] and [0002] of the specification as originally filed, as well as in original Figs. 1 and 4.

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).

Applicants thank Examiner Kruer for the courtesies extended to their representative during the March 17, 2003, personal interview. Applicants' separate record of the substance of the interview is incorporated into the following remarks.

Claims 1 and 2 are rejected under 35 U.S.C. §102 over Gause et al. Applicants respectfully traverse the rejection.

Gause is directed to unclad or metal clad laminates constructed by sandwiching a resin impregnated core of paper between epoxy resin impregnated woven glass fabric sheets.

See the Abstract. Gause also teaches that metal foil may be bonded directly to one or both of the outer woven glass layers during the fabrication of the laminate. Col. 4, lines 14-17. See also Figs. 2 and 3.

Gause does not teach a paper phenolic resin copper-clad laminate in which copper foils adapted to have terminals of electronic components soldered thereon are laminated on a face side of a phenolic resin impregnated paper base and resists are applied on the same face side of the phenolic resin impregnated paper base as the copper foils, except an area adapted to have the terminals of the electronic components soldered on the copper foils. Therefore, Gause does not teach or suggest each and every feature of claim 1. As a result, the rejection under 35 U.S.C. §102 over Gause should be reconsidered and withdrawn.

Claims 1 and 2 are also rejected under 35 U.S.C. §102 over Nomura. Applicants respectfully traverse the rejection.

Nomura is directed to a base board comprising at least one sheet of prepreg comprising a thermosetting resin as an impregnant and a layer comprising a composition of a semi-cured thermosetting resin and a nitrile rubber on one or both sides of the prepreg layer. See the Abstract. Nomura specifically teaches the use of this base board for printing circuits prepared by the additive process. See the Abstract. In the additive process, metal is plated on the base board, masking ink is plated on the metal layer to form the circuit pattern, metal is plated in the areas not plated by the masking ink, and the masking ink layer is then removed. See col. 2, lines 1-27 and the examples.

Nomura does not teach a single-sided paper phenolic resin copper-clad laminate in which copper foils adapted to have terminals of electronic components soldered thereon are laminated on a face side of a phenolic resin impregnated paper base, resists are applied on the same face side of the phenolic resin impregnated paper base as the copper foils, except an area adapted to have the terminals of electronic components soldered on the copper foils, and resists formed of a same material as the resists on the face side are applied on a reverse side

of the phenolic resin impregnated paper base. Therefore, the rejection under 35 U.S.C. §102 over Nomura should be reconsidered and withdrawn.

Claims 3-8 have been added to further define the invention. Claims 3-8 ultimately depend from claim 1 and are therefore patentable for at least the reasons discussed above with regard to claim 1.

In view of the foregoing amendments and remarks, Applicants submit that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1-8 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicants' undersigned representative at the telephone number set forth below.

Respectfully submitted,

James A. Oliff
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JAO:MLM/jam

Attachment:
Appendix

Date: April 15, 2003

OLIFF & BERRIDGE, PLC
P.O. Box 19928
Alexandria, Virginia 22320
Telephone: (703) 836-6400

DEPOSIT ACCOUNT USE AUTHORIZATION
Please grant any extension necessary for entry;
Charge any fee due to our Deposit Account No. 15-0461

APPENDIX

Changes to Claims:

Claims 3-8 are added.

The following is a marked-up version of the amended claim:

1. (Amended) A single-sided paper phenolic resin copper-clad laminate ~~composed of~~comprising a phenolic resin impregnated paper base having:

-_____copper foils adapted to have terminals of electronic components soldered thereon, the copper foils being laminated on a face side of said phenolic resin impregnated paper base, and

_____resists applied on ~~a~~ the face side ~~thereof~~, except an area adapted to have the terminals of electronic components soldered on the copper foils,

_____-wherein resists formed of a same material as the resists on the face side are applied on a reverse side of the phenolic resin impregnated paper base.